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**INLINE DIE-ATTACH  
 ME8650-RCT**

- Flexible**
- Moisture Resistant**
- 100% Solid**
- Rapid Curing**

**IDEAL FOR:**

- "Low" Bleeding**
- Large Area Die Attach**
- Higher Thermal Conductivity**
- Component Attach**
- Substate Attach**

**DESCRIPTION:**

ME8650-RCT is a higher thermally conductive version of ME 8650-RC. It is designed for needle dispensing and screen-printing processing. This silver filled conductive die-attach adhesive can be rapidly cured at low temperatures. This single component, silver filled paste is ambient storable electrically and thermally conductive. It is highly thixotropic with minimal sag.

ME8650-RCT has been designed to eliminate bleeding on both silver plated copper and alloy 42 leadframes. It is 100% solid for inline rapid curing applications. Maintain more than 100 psi bond strength at 250°C for wire-bonding.

**AVAILABILITY:**

ME8650-RCT is available in syringes or in jars.

**APPLICATION PROCEDURES:**

- ( 1 ) Thaw for 30 min. before opening jar or using syringes.
- ( 2 ) Dispense adhesive onto clean substrate with a suitable pattern to assure full die coverage.
- ( 3 ) Cure according to one of the recommended CURE SCHEDULES.

**TYPICAL PROPERTIES\***

Electrical Resistivity ( 150 °C/ 5 minutes )	<3x10 <sup>-4</sup> ohm-cm
Dielectric Strength (Volts/mil)	Not Applicable
Glass Transition Temp.(°C)	-20/-50 Minor
Current Carrying Capabilities	50 Amp/mm <sup>2</sup>
Lap-Shear Strength	
Device Push-off Strength	>2000 psi >133.8 N/mm <sup>2</sup>
Hardness (Type)	85 (A)
Cured Density (gm/cc)	4.0
Thermal Conductivity	>55 Btu-in/hr-ft <sup>2</sup> -°F >7.9 W/m-°C
Linear Thermal Expansion Coeff. (ppm/°C)	100
Maximum Continuous Operation Temp. (°C)	150
Avg. Viscosity(5.0 rpm, 24°C) (Brookfield DV-1,spindle CP51)	20,000 cp

\* Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is intended to be used in manufacturing and in the final product.

**CURE SCHEDULES:**

<u>Temperature</u>	<u>Time</u>
125°C	30 min
150°C	15 min
175°C	8 min

Pot life: 25°C for 30 days.

**SHELF LIFE:**

<u>Storage temperature</u>	<u>Shelf Life</u>
-40°C	1 yr
25°C	30 day

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